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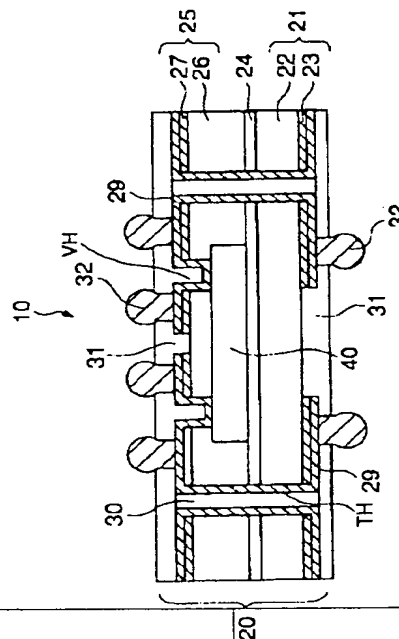
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(54) **SEMICONDUCTOR DEVICE AND
MANUFACTURING METHOD THEREFOR**

(57) Abstract:

PROBLEM TO BE SOLVED: To realize high performance by enabling compact constitution when a semiconductor element is mounted in a package and facilitating three-dimensional arrangement constitution and mutual connection of semiconductor elements if necessary in a semiconductor device.

SOLUTION: A thin semiconductor chip 40 of about 50 μm in thickness is buried and mounted in a package 20. External connection terminals 32 are formed on both surfaces of the package 20, or a terminal forming part of a wiring pattern 29 with which the external connection terminals are to be connected is exposed from a solder resist layer 31 and constituted in such a manner that multilayer stacking is possible.



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